

REVISED RECORD LIST

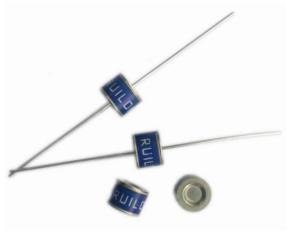
Rev.	Date	Revised Content
1.0	2023-06-13	Initial version



Gas Discharge Tube

GDT is placed in front of, and in parallel with, sensitive telecom equipment such as power lines, communication lines, signal lines and data transmission lines to help protect them from damage caused by transient surge voltages that may result from lightning strikes and equipment switching operations. These devices do not influence the signal in normal operation. However, in the event of an overvoltage surge, such as a lightning strike, the GDT switches to a low impedance state and diverts the energy away from the sensitive equipment..

Our GDT offer a high level of surge protection, a broad voltage range, low capacitance, and many form factors including new surface mount devices, which makes them suitable for applications such as Main Distribution Frame (MDF) modules, high data-rate telecom applications (e.g. ADSL, VDSL), and surge protection on power lines. Their low capacitance also results in less signal distortion. When used in a coordinated circuit protection solution with PolySwitch devices, they can help equipment manufacturers meet stringent safety regulatory standards.



Features

- Excellent response to fast rising transients
- Stable breakdown voltage
- GHz working frequency
- 8/20μs Impulse current capability: 10KA
- Non-Radioactive
- Ultra Low capacitance (<1.5pF)
- Lead-free compliant
- RoHS and REACH complian
- Size: Φ8mm*6mm
- Storage and operational temperature: -40~+90 °C

Automotive:

MDF modules

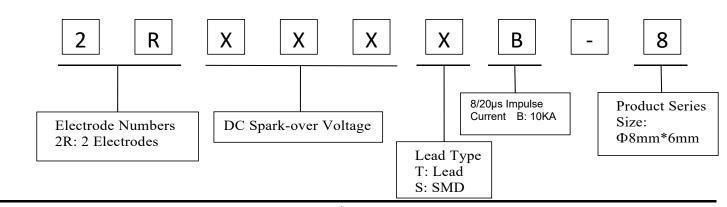
Applications

- xDSL equipment
- RF systems
- Antenna
- Base stations
- Repeaters, Modems
- Telephone Interface, Line cards

Others:

- Data communication equipment
- Line test equipment
- Power supplies
- Surge protectors, Alarm systems

Part Number Code





Electrical symbol





Electrical Characteristics

		P.G	Impulse Spark	_		Capacitance @1MHz	Glow Voltage @10mA	Arc Voltage @1A	Arc Voltage @1A			
	Part Vo	DC Spark-over Voltage ^{1) 2} @100V/S	100 V/μS	1KV/μS						ulse Discharge rent@8/20µS	AC Discharge Current @50Hz 1S	Impulse Life @10/100μS 100A
			Max	Max	Min	Max	Туре	77120	Nominal ±5 times	Max 1 time	Nominal 10 times	Min
DIP	SMD	V	V	V	GΩ	pF	V	V	KA	KA	A	Times
2R075TB-8 ⁴	2R075SB-8 ⁴⁾	75±20%	500	600	1	1.5	60	10	10	20	10	300
2R090TB-8	2R090SB-8	90±20%	500	600	1	1.5	60	10	10	20	10	300
2R150TB-8	2R150SB-8	150±20%	500	600	1	1.5	60	10	10	20	10	300
2R230TB-8	2R230SB-8	230±20%	600	700	1	1.5	60	10	10	20	10	300
2R250TB-8 ⁴⁾	2R250SB-8 ⁴⁾	250±20%	600	700	1	1.5	60	10	10	20	10	300
2R300TB-8	2R300SB-8	300±20%	700	800	1	1.5	60	10	10	20	10	300
2R350TB-8	2R350SB-8	350±20%	700	800	1	1.5	60	10	10	20	10	300
2R400TB-8	2R400SB-8	400±20%	750	850	1	1.5	135	15	10	20	10	300
2R420TB-8	2R420SB-8	420±20%	750	850	1	1.5	135	15	10	20	10	300
2R470TB-8	2R470SB-8	470±20%	800	900	1	1.5	135	15	10	20	10	300
2R600TB-8	2R600SB-8	600±20%	900	1000	1	1.5	135	15	10	20	10	300
2R800TB-8	2R800SB-8	800±20%	1200	1400	1	1.5	135	15	10	20	10	300

Glow to Arc transition Current	~0.5A		
Weight	DIP 1.5g SMD ~1.25g		
Operation and storage temperature	-40∼+90°C		
Marking, red negative	RUILON XXX Y XXX -Nominal voltage Y -Year of production		
Surface treatment	DIP -Nickel Plated SMD -Matte-tin plated		

- 1) At delivery AQL 0.65 level II, DIN ISO 2859.
- 2) In ionized mode.
- 3) Insulation Resistance Measuring Voltage:

75V~150V at DC 50V Other at DC 100V

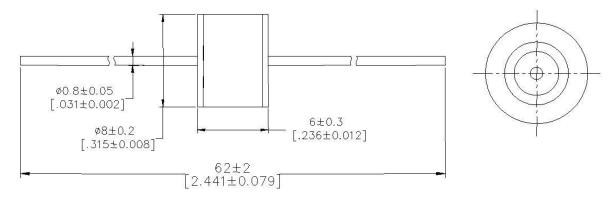
4) No UL recognized.

Terms in accordance with ITU-T Rec. K.12, IEC 61643-311, GB/T18802.311, GB/T 9043.

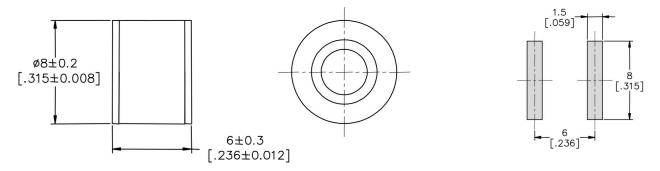


Dimensions (Unit: mm/inch)

DIP Series (2RxxxTB-8)



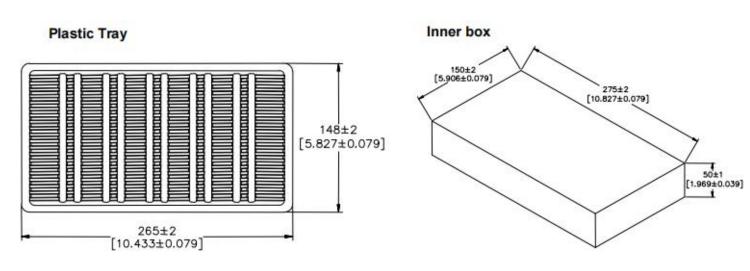
SMD Series (2RxxxSB-8)



Recommended Soldering Pad Layout

Packaging Information (Unit: mm/inch)

Axial Packaging (Bulk)

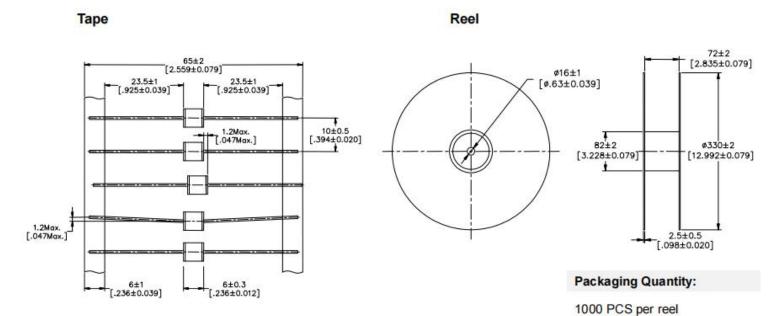


Packaging Quantity:

100 PCS per Plastic Tray5 Plastic Trays per inner box500 PCS per inner box

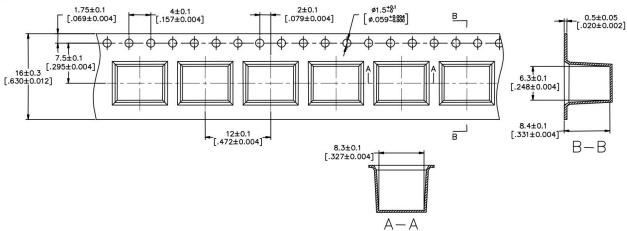


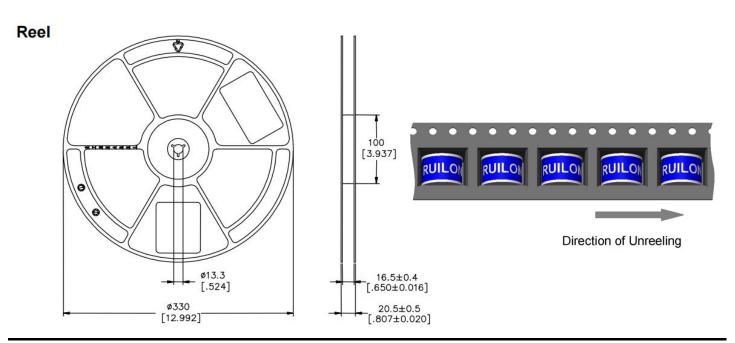
Axial Packaging (Tape & Reel)



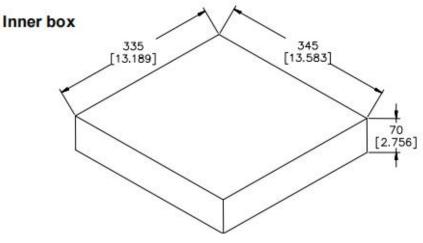
SMD Packaging (Tape & Reel)

Tape





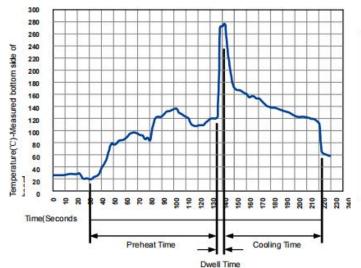




Packaging Quantity: 500 PCS per (13")

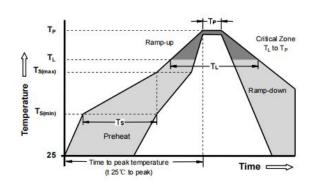
3 reels per inner box 1500 PCS per inner box

Soldering Parameters - Wave soldering (Thru-Hole Devices)



Wave Soldering Condition		Pb-Free assembly	
	Temperature Min	100°C 150°C 60-180 Seconds	
Preheat	Temperature Max		
	Time (Min to Max)		
Solder Pot Temperature		280°C Max	
Solder Dwell Time		2-5 Seconds	

Soldering Parameters - Reflow Soldering (Surface Mount Devices)



Reflow Co	ndition	Pb - Free assembly		
	-Temperature Min (T _{s(min)})	150°C		
Preheat	-Temperature Max (T _{s(max)})	200°C		
	- Time (min to max) (t _s)	60 -180 Seconds		
Average ramp up rate (Liquids Temp T _L) to peak		3°C/second max		
T _{S(max)} to T	L - Ramp-up Rate	5°C/second max		
Reflow	- Temperature (T _L) (Liquids)	217°C		
	- Time (min to max) (t _s)	60 -150 Seconds		
Peak Tem	perature (T _P)	260 +0/-5°C		
Time within 5°C of actual peak Temperature (t _p)		10 - 30 Seconds		
Ramp-dow	n Rate	6°C/second max		
Time 25°C to peak Temperature (T _P)		8 minutes Max		
Do not exceed		260°C		